TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK3130

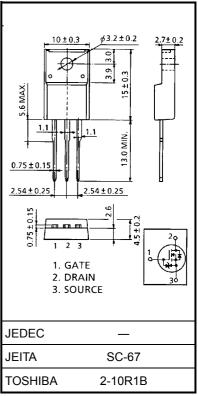
Switching Regulator Applications

Unit: mm

- Reverse-recovery time: $t_{rr} = 85 \text{ ns}$
- Built-in high-speed flywheel diode
- Low drain-source ON resistance: RDS (ON) = 1.12Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 5.0 \text{ S (typ.)}$
- Low leakage current: $IDSS = 100 \mu A (max) (VDS = 600 V)$
- Enhancement-model: $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit		
Drain-source voltage			V_{DSS}	600	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)			V_{DGR}	600	V	
Gate-source voltage			V _{GSS}	±30	V	
Drain current	DC (N	lote 1)	I _D	6	Α	
	Pulse (N	lote 1)	I _{DP}	24		
Drain power dissipation (Tc = 25°C)			P_{D}	40	W	
Single pulse avalanche energy (Note 2)			E _{AS}	345	mJ	
Avalanche current			I _{AR}	6	Α	
Repetitive avalanche energy (Note 3)			E _{AR}	4	mJ	
Channel temperature			T _{ch}	150	°C	
Storage temperature range			T _{stg}	-55~150	°C	



Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 16.8 mH, $R_G = 25 \Omega$, $I_{AR} = 6 \text{ A}$

Note 3: Repetitive rating; pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution

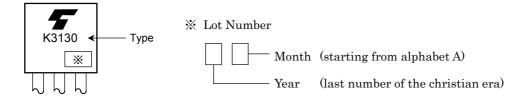
Electrical Characteristics (Ta = 25°C)

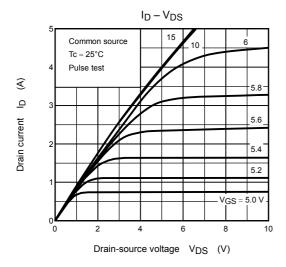
Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage curr	ent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Gate-source breal	kdown voltage	V (BR) GSS	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-OFF cur	rent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	100	μА
Drain-source brea	kdown voltage	V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	600	_	_	V
Gate threshold vo	Itage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON	resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 3 A	_	1.12	1.55	Ω
Forward transfer a	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3 A	1.5	5.0	_	S
Input capacitance		C _{iss}		_	1300	_	
Reverse transfer capacitance		C _{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	130	_	pF
Output capacitance		C _{oss}		_	400	_	
Turn-ON Switching time	Rise time	t _r	$V_{GS} = 3 \text{ A} V_{OUT} = 3 \text{ A} V_{OUT} = 100 \Omega$ $V_{GS} = 100 \Omega$ $V_{DD} \approx 300 \text{ V}$ $V_{DD} \approx 100 \text{ A}$ $V_{DD} \approx 300 \text{ V}$	_	25	_	- ns
	Turn-ON time	t _{on}			45	_	
	Fall time	t _f			40		
	Turn-OFF time	t _{off}		_	150	_	
Total gate charge (gate-source plus gate-drain)		Qg			30		nC
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$		18		
Gate-drain ("miller") charge		Q _{gd}		_	12	_	

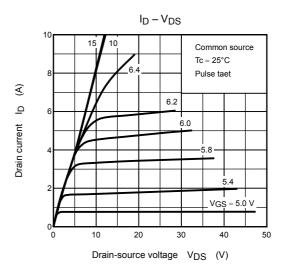
Source-Drain Ratings and Characteristics (Ta = 25°C)

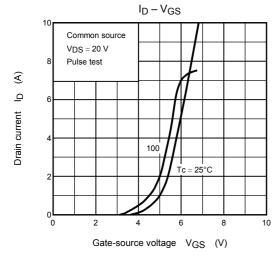
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	_	_	_	6	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	24	Α
Forward voltage (diode)	V_{DSF}	$I_{DR} = 6 A$, $V_{GS} = 0 V$	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V},$		85	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} /dt = 100 A/μs	_	0.21	_	μС

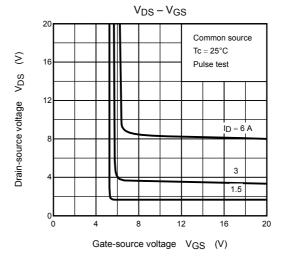
Marking

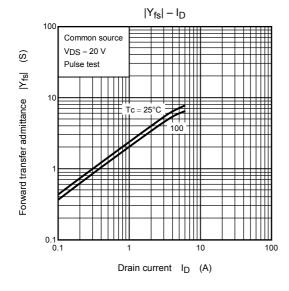


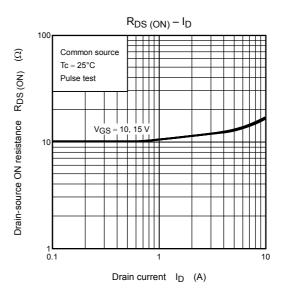




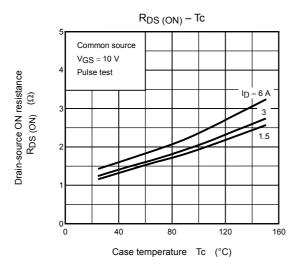


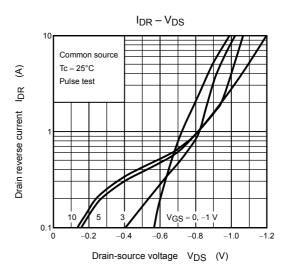


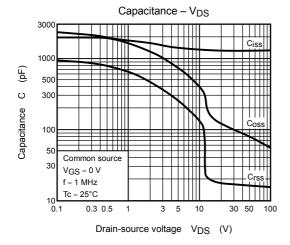


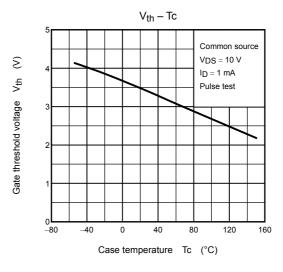


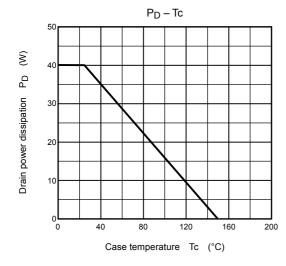
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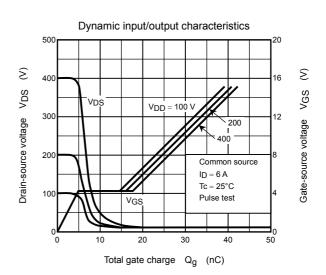




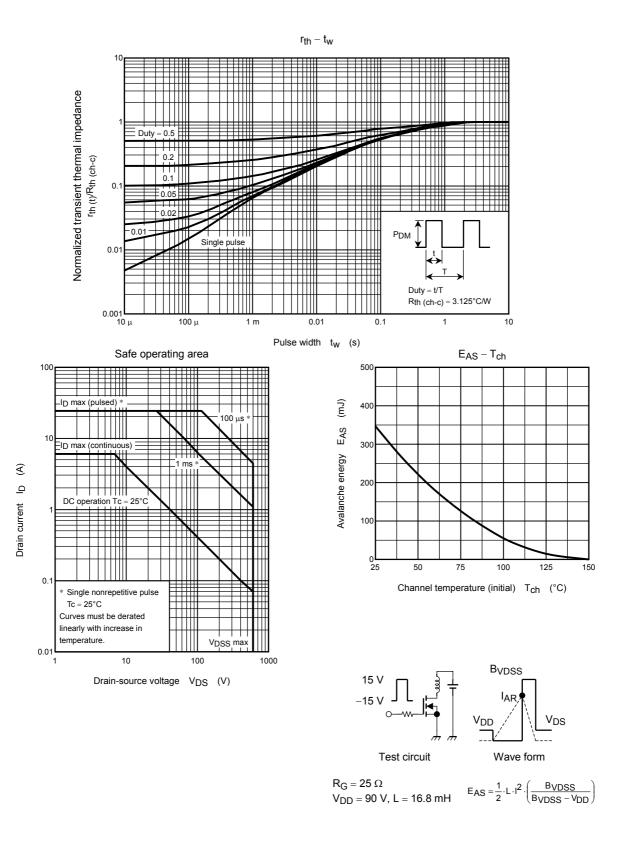








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